

苏州杭晶电子科技有限公司

产品规格书 Product Specification

CUSTOMER	客户:	
CUSTOMER PN	客户 PN:	
HANG CRYSTAL P/N	杭晶物料编码:	8121S-32.000NN18DTL
MODEL	产品型号:	TCXO SMD 2.0x1.6, Sine wave, 1.8V
NOMINAL FREQUENCY	频率:	32.000MHz
•		
ISSUE DATE	日期:	2022 / 11 / 11

CUSTOMER'S APPROVAL

客户确认

APPROVED QA

MB. J.Jiang

(PLEASE RETURN A COPY WITH APPOVAL) (请将确认的复印件返回我司)

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Revision	Description / ECN	Prepared	Approved	Date
1	Initial release	MB	James Jiang	2022-11-11
2	Not issued			
3	Not issued			
4	Not issued			

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1. NOMINAL AND MAXIMUM RATINGS, OPERATING AND STORAGE CONDITIONS

	PARAMETER	SYMB.	MIN	TYP	MAX	Unit	Conditions / Remarks
1	Nominal frequency	F _N		32.000		MHz	
2	Maximum supply voltage	V _{MAX}	-0.3		+4.6	V _{DC}	Between V _{CC} and GND
3	Nominal supply voltage	Vcc	+1.71	+1.80	+1.89	V _{DC}	
4	Output load (resistive)	RL	9	10	11	Ω	Clipped sine wave output
5	Output load (capacitive)	CL	9	10	11	pF	Clipped sine wave output
6	Operating temperature range	T _{OP}	-40	+25	+85	°C	Note 1
7	Storage Temperature Range	T _{ST}	-4 0		90	°C	
8	Enable / Disable function	E/D		ot availat			Pin 1 GND

Note 1: Unit stays within all relevant parameter limits as specified under point 2

2. ELECTRICAL PARAMETER LIMITS

	PARAMETER	SYMB.	MIN	TYP	MAX	Unit	Conditions / Remarks
1	Frequency calibration	Δf/F _N	-1.0		+1.0	ppm	Offset from nominal at +25°C
2	Frequency stability over TOP	Δf/F _{OP}	-1.0		+1.0	ppm	Over T _{OP} –40~+85°C; Note 1
3	Frequency VS voltage changes	∆f/F∨	-0.2		+0.2	ppm	Vcc ±5% at +25°C
4	Frequency VS load changes	Δf/F _L	-0.2		+0.2	ppm	RL//CL ±5% at +25°C
5	Aging first year	Δf/F _{A1}	-1.0		+1.0	ppm	at +25°C
6	Output amplitude voltage level	V _{P-P}	0.8	1.1		V _{AC}	Clipped sine wave DC coupled
7	Phase noise at 100Hz offset	L _{RMS}		-118		dBc/Hz	at +25°C
	at 1kHz offset	L _{RMS}		-135		dBc/Hz	at +25°C
	at 10kHz offset	L _{RMS}		-140		dBc/Hz	at +25°C
	at 100kHz offset	L _{RMS}		-145		dBc/Hz	at +25°C
8	Current consumption	Icc			2.0	mA	Under load RL//CL ±10%
9	Startup time	tstrt			2.0	ms	V _{P-P} reach >90% of amplitude

Note 1: Referenced to midpoint between minimum and maximum frequency over specified temperature range.

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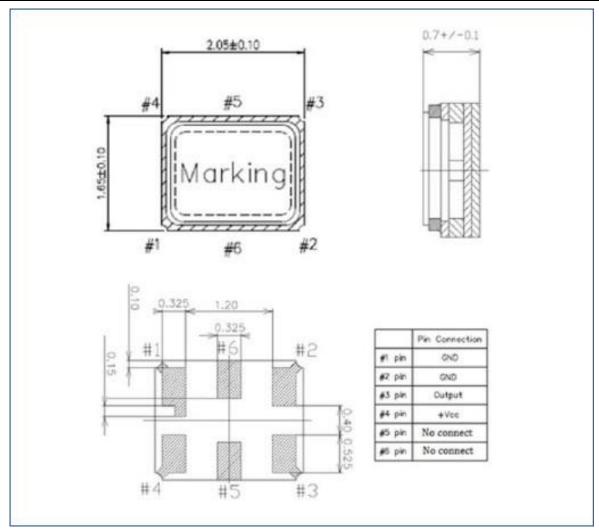
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3. PRODUCT MARKING

TBD

4. OUTLINE DRAWING

Package description	Package model	Remarks
Ceramic seam seal SMD package 2.0x1.6mm with 4 pads for TCXO	CST2016p4sph70	



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5. RELIABILITY TEST INFORMATION

	Test item	Test conditions	Criteria
1	High temperature storage	Temperature: +125°C ±5°C Time: 240 ±4 Hours Tested after 4 to 12h at room temperature.	±1.0ppm
2	Low temperature storage	Temperature: -55°C ±5°C Time: 240 ±4 Hours Tested after 4 to 12h at room temperature.	±1.0ppm
3	Temperature humidity bias THB	Temperature: +85°C ±5°C Humidity: 85% ±5% RH Time: 240 ±4 Hours BIAS: Supply Voltage Tested after 4 to 12h at room temperature.	±1.0ppm
4	Temperature cycling	Low Temp. cycle: -55°C ±2°C High Temp. cycle: +85°C ±5°C Time: 30min each cycle Number of cycles: 1,000 Tested after 4 to 12h at room temperature.	±1.0ppm
5	Aging	Temperature: +85°C ±5°C Time: 30d Tested after 4 to 12h at room temperature.	±1.0ppm
6	Resistance to solder heat	Reflow peak temp.: +260°C ±5°C (refer to rec. profile) Number of cycles: 3 times Tested after 4 to 12h at room temperature.	±1.0ppm
7	Solderability (MIL-STD-883E)	Dip in flux: 5~10 Seconds Temperature: 230°C ±10°C Time: 5 Seconds Tested after 4 to 12h at room temperature.	>95% cover.
8	Drop test	Drop height: 120cm Number of cycles: 12 times Drop height: 150cm Number of cycles: 9 times With jig (120~150g) onto iron plate Tested after 24h at room temperature.	±1.0ppm
9	Vibration	Frequency Range: 20~2000Hz PSD: 0.053g² Time: 40min each direction (X,Y,Z) Tested after 4 to 12h at room temperature.	±1.0ppm
10	ESD-HBM	HBM, V=±1KV, C=100pF, R1=10M, R2=1.5K, 3times	±1.0ppm

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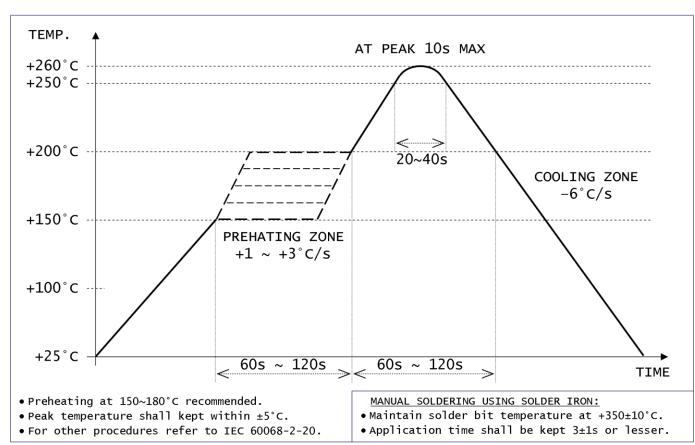
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6. ENVIRONMENTAL COMPLIANCE INFORMATION

		Compliance information	
1	RoHS	This product is fully RoHS compliant, 6/6 compliant per EU legislation.	
2	RoHS 2	In regards of RoHS 2, CE marking directive for finished products, we can provid RoHS test reports and MDS to show compliance, but since our product is not a final application we have no CE mark.	
3	Lead-Free	This product is considered Lead-Free, Lead (Pb) contamination is controlled to be below 200ppm.	
4	Halogen-Free	This product is compliant to IEC 61249-2-21:2003 (Br<800ppm / Cl<800ppm).	
5	REACH (SVHC)	This product does not contain substances (SVHC) listed by REACH, we continuously monitor updates of the list of SVHC's	
6	PFOS / PFOA Free	This product is free of any PFOS / PFOA.	
7	Electrostatic Discharge (ESD) sensitivity	This product is ESD sensitive and requires precautions for handling and storage. Follow JEITA EIAJ ED-4701 or JSD22 or ANSI-ESD-S20-20 or IEC 61000-4-2.	
8	Moisture Sensitivity	This product is hermetically sealed and does NOT fall under the classification of moisture sensitivity per J-STD-020C (Standard is for non-hermetically sealed components). If required we suggest to use LEVEL 1	

7. RECOMMENDED SOLDERING INFORMATION

RECOMMENDED REFLOW SOLDER PROFILE - PEAK TEMPERATURE UP TO +260°C



DWG_ReflowProfile_260

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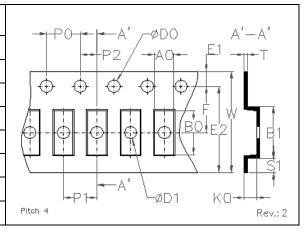


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8. PACKAGING

<u>Carrier</u>

	Parameter	STANDARD PACKAGING	ALTERNATE PACKAGING			
1	A0	1.85±0.1				
2	В0	2.25±0.1				
3	K0	1.05±0.1				
4	B1	2.85±0.1				
5	P0	4.0±0.1				
6	P1	4.0±0.1				
7	Т	0.3±0.05				
8	W	8.0±0.2				
NI-4- 4	Nata 4. All discoursions in formal					



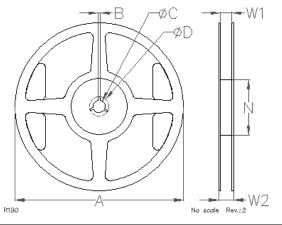
Note 1: All dimensions in [mm].

Note 2: All dimensions not specified or not being shown follow EIA-481 standard.

Reel

QTY per reel: 3,000pcs MAX

	Parameter	STANDARD PACKAGING	ALTERNATE PACKAGING
9	А	180 ⁺⁰ –1.5	
10	В	2.0±0.5	
11	ØC	13±0.2	
12	ØD	21±0.8	
13	N	60±2	
14	W1	9.0±0.3	
15	W2	11.4±1.0	

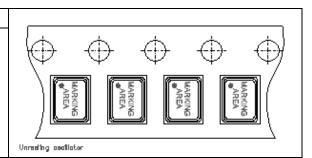


Note 1: All dimensions in [mm]. Dimension W1 is measured near the Hub (N). Note 2: All dimensions not specified or not being shown follow EIA-481 standard.

Unreeling information

Oscillator product's orientation

This product is a polarized component which requires a certain orientation; Pin 1 is identified on top side marking with a DOT. In the carrier tape is the component oriented with pin 1 towards the sprocket holes. (per EIA-481)



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